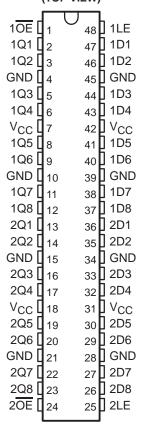
SCES067F - JUNE 1996 - REVISED JANUARY 1999

- State-of-the-Art Advanced BiCMOS Technology (ABT) Widebus™ Design for 2.5-V and 3.3-V Operation and Low Static **Power Dissipation**
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V<sub>CC</sub>)
- **Typical V<sub>OLP</sub> (Output Ground Bounce)**  $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- High Drive (-24/24 mA at 2.5-V and -32/64 mA at 3.3-V V<sub>CC</sub>)
- **Power Off Disables Outputs, Permitting Live Insertion**
- **High-Impedance State During Power Up** and Power Down Prevents Driver Conflict
- Uses Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- **Auto3-State Eliminates Bus Current** Loading When Output Exceeds V<sub>CC</sub> + 0.5 V
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model; and Exceeds 1000 V **Using Charged-Device Model, Robotic** Method
- Flow-Through Architecture Facilitates **Printed Circuit Board Layout**
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

#### SN54ALVTH16373 . . . WD PACKAGE SN74ALVTH16373... DGG, DGV, OR DL PACKAGE (TOP VIEW)



#### description

The 'ALVTH16373 devices are 16-bit transparent D-type latches with 3-state outputs designed for 2.5-V or 3.3-V  $V_{
m CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated

SCES067F - JUNE 1996 - REVISED JANUARY 1999

#### description (continued)

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When  $V_{CC}$  is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

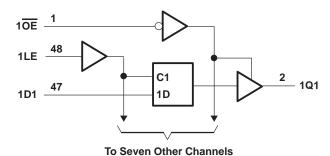
The SN54ALVTH16373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALVTH16373 is characterized for operation from –40°C to 85°C.

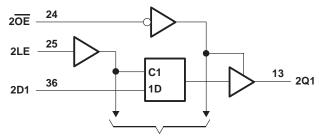
## FUNCTION TABLE (each 8-bit section)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	X	Χ	Z



#### logic diagram (positive logic)





To Seven Other Channels

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	-0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Output current in the low state, IO: SN54ALVTH16373	96 mA
SN74ALVTH16373	
Output current in the high state, I <sub>O</sub> : SN54ALVTH16373	–48 mA
SN74ALVTH16373	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T <sub>sta</sub> –	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

#### recommended operating conditions, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (see Note 3)

			SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vcc	Supply voltage				2.7	2.3		2.7	V
VIH	High-level input voltage		1.7			1.7			V
V <sub>IL</sub>	Low-level input voltage		4	0.7			0.7	V	
VI	Input voltage	0	VCC	5.5	0	VCC	5.5	V	
ІОН	High-level output current			,0	-6			-8	mA
la	Low-level output current			Ç	6			8	mΑ
lor	Low-level output current; current duty cycle ≤	50%; f≥1 kHz	5	5	18			24	IIIA
Δt/Δν	Input transition rise or fall rate	St.		10			10	ns/V	
Δt/ΔV <sub>CC</sub>	Power-up ramp rate	200			200			μs/V	
TA	Operating free-air temperature	-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51.

SCES067F - JUNE 1996 - REVISED JANUARY 1999

## recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V $\pm$ 0.3 V (see Note 3)

			SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage	3		3.6	3		3.6	V	
VIH	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage		4	0.8			0.8	V	
VI	Input voltage	0	VCC	5.5	0	VCC	5.5	V	
IOH	High-level output current			Q	-24			-32	mA
la	Low-level output current			(0)	24			32	mA
lOL	Low-level output current; current duty cycle ≤ 50%; f ≥ 1 kHz				48			64	IIIA
Δt/Δν	Input transition rise or fall rate	8		10			10	ns/V	
Δt/ΔV <sub>CC</sub>	Power-up ramp rate	200		·	200			μs/V	
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SCES067F - JUNE 1996 - REVISED JANUARY 1999

# electrical characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted)

	ND AMETED	TEST O	ONDITIONS	SN54	ALVTH1	6373	SN74	ALVTH1	6373	LINUT
PA	ARAMETER	TEST	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		$V_{CC} = 2.3 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OH} = -100 \mu A$	V <sub>CC</sub> -0.	2		V <sub>CC</sub> -0	.2		
VOH		V <sub>CC</sub> = 2.3 V	I <sub>OH</sub> = -6 mA	1.8						V
		vCC = 2.3 v	I <sub>OH</sub> = -8 mA				1.8			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I <sub>OL</sub> = 100 μA			0.2			0.2	
			I <sub>OL</sub> = 6 mA			0.4				
VOL		V <sub>CC</sub> = 2.3 V	$I_{OL} = 8 \text{ mA}$						0.4	V
		V(C) = 2.5 V	I <sub>OL</sub> = 18 mA			0.5				
			I <sub>OL</sub> = 24 mA						0.5	
	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V <sub>I</sub> = 5.5 V			<u>\$</u> 10			10	
II		a inputs $V_{CC} = 2.7 \text{ V}$	V <sub>I</sub> = 5.5 V		, i	10			10	μΑ
	Data inputs		VI = VCC		27	1			1	
			V <sub>I</sub> = 0		1	<b>-</b> 5			<b>–</b> 5	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$		25				±100	μΑ
I <sub>BHL</sub> ‡		$V_{CC} = 2.3 \text{ V},$	V <sub>I</sub> = 0.7 V		115			115		μΑ
IBHH§		$V_{CC} = 2.3 \text{ V},$	V <sub>I</sub> = 1.7 V	Q	-10			-10		μΑ
I <sub>BHLO</sub>	,¶	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to $V_{CC}$	300			300			μΑ
Івннс	) <sup>#</sup>	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to $V_{CC}$	-300			-300			μΑ
<sub>IEX</sub>		$V_{CC} = 2.3 \text{ V},$	$V_0 = 5.5 \text{ V}$			125			125	μΑ
IOZ(Pl	J/PD) <sup>☆</sup>	$V_{CC} \le 1.2 \text{ V}, V_{O} = 0.5 \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}} = 0.5 \text{ V}$	√ to V <sub>CC</sub> , = don't care			±100			±100	μΑ
lozh Vcc		V <sub>CC</sub> = 2.7 V	$V_O = 2.3 \text{ V},$ $V_I = 0.7 \text{ V or } 1.7 \text{ V}$			5			5	μΑ
lozL		V <sub>CC</sub> = 2.7 V	$V_O = 0.5 \text{ V},$ $V_I = 0.7 \text{ V or } 1.7 \text{ V}$			-5			-5	μΑ
		V <sub>CC</sub> = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
Icc		$I_{O} = 0$ ,	Outputs low	1	2.3	4.5		2.3	4.5	┥
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V <sub>CC</sub> = 2.5 V,	V <sub>I</sub> = 2.5 V or 0	1	3.5			3.5		pF
Co		V <sub>CC</sub> = 2.5 V,	V <sub>O</sub> = 2.5 V or 0	1	6			6		pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 2.5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>&</sup>lt;sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>IL</sub> max.

<sup>§</sup> The bus-hold circuit can source at least the minimum high sustaining current at V<sub>IH</sub> min. I<sub>BHH</sub> should be measured after raising V<sub>IN</sub> to V<sub>CC</sub> and then lowering it to V<sub>IH</sub> min.

<sup>¶</sup> An external driver must source at least IBHLO to switch this node from low to high.

<sup>#</sup>An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

<sup>\*</sup>High-impedance state during power up or power down

SCES067F - JUNE 1996 - REVISED JANUARY 1999

# electrical characteristics over recommended operating free-air temperature range, $V_{\text{CC}}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
PA	RAMEIER	1531 C	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP†	MAX	UNII
VIK		V <sub>CC</sub> = 3 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0.	2		V <sub>CC</sub> -0	.2		
Vон		V 2.V	I <sub>OH</sub> = -24 mA	2						V
		VCC = 3 V	I <sub>OH</sub> = -32 mA				2			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I <sub>OL</sub> = 100 μA			0.2			0.2	
			I <sub>OL</sub> = 16 mA						0.4	
VOL			I <sub>OL</sub> = 24 mA			0.5				V
VOL		V <sub>CC</sub> = 3 V	$I_{OL} = 32 \text{ mA}$						0.5	V
			$I_{OL} = 48 \text{ mA}$			0.55				
	_		$I_{OL} = 64 \text{ mA}$						0.55	
Control inputs		$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V <sub>I</sub> = 5.5 V		Á	10			10	
l <sub>l</sub>			V <sub>I</sub> = 5.5 V		72/2	10			10	μΑ
	Data inputs	$V_{CC} = 3.6 \text{ V}$	VI = VCC		1	1			1	
			V <sub>I</sub> = 0		2	<b>-</b> 5			<b>–</b> 5	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$	0	2				±100	μΑ
I <sub>BHL</sub> ‡		V <sub>CC</sub> = 3 V,	V <sub>I</sub> = 0.8 V	75			75			μΑ
I <sub>BHH</sub> §		V <sub>CC</sub> = 3 V,	V <sub>I</sub> = 2 V	-75			-75			μΑ
<sup>I</sup> BHLO	1	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to $V_{CC}$	500			500			μΑ
Івнно	<b>,</b> #	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to $V_{CC}$	-500			-500			μΑ
I <sub>EX</sub>		$V_{CC} = 3 V$ ,	V <sub>O</sub> = 5.5 V			125			125	μΑ
IOZ(PL	J/PD)☆	$V_{CC} \le 1.2 \text{ V}, V_{O} = \underline{0.5} \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}} = \underline{0.5} \text{ V}$	V to V <sub>CC</sub> , = don't care			±100			±100	μΑ
lozh		V <sub>CC</sub> = 3.6 V	V <sub>O</sub> = 3 V,			5			5	μΑ
			V <sub>I</sub> = 0.8 V or 2 V							
lozL		V <sub>CC</sub> = 3.6 V	$V_0 = 0.5 \text{ V},$			-5			-5	μΑ
			V <sub>I</sub> = 0.8 V or 2 V	┼	0.07		<u> </u>		0.4	
Icc		$V_{CC} = 3.6 \text{ V},$	Outputs high		0.07	0.1		0.07	0.1	
		$I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs low	-	3.2	5.5		3.2	5	mA
			Outputs disabled	₩	0.07	0.1		0.07	0.1	
ΔlCC□		V <sub>CC</sub> = 3 V to 3.6 V, One Other inputs at V <sub>CC</sub> or	e input at V <sub>CC</sub> – 0.6 V, GND			0.4			0.4	mA
C <sub>i</sub>		$V_{CC} = 3.3 \text{ V},$	$V_{I} = 3.3 \text{ V or } 0$		3.5			3.5		pF
Co		V <sub>CC</sub> = 3.3 V,	V <sub>O</sub> = 3.3 V or 0		6			6		pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>&</sup>lt;sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>II</sub> max.

<sup>§</sup> The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

 $<sup>\</sup>P$  An external driver must source at least  $I_{\mbox{\footnotesize{BHLO}}}$  to switch this node from low to high.

<sup>#</sup> An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

<sup>★</sup>High-impedance state during power up or power down

<sup>□</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

SCES067F - JUNE 1996 - REVISED JANUARY 1999

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

			SN54ALVTH16373	SN74ALVTH	116373	UNIT
		MIN MAX	MIN	MAX	UNIT	
t <sub>W</sub>	Pulse duration, LE high	1.5	1.5		ns	
	Octor force data to force LE	Data high	1.1,0	1		
t <sub>su</sub>	Setup time, data before LE↓	Data low	1.6	1.5		ns
+.	Hold time, data after LE↓	Data high	\$1	0.9		ns
t <sub>h</sub>	noid time, data after LE↓	1.6	1.5		115	

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

			SN54ALVTI	H16373	SN74ALVT	H16373	UNIT	
				MAX	MIN	MAX	ONIT	
t <sub>W</sub>	Pulse duration, LE high		1.5	\\\ \( \) \( \) \( \)	1.5		ns	
	Cotum time data before I E	Data high	1.5		1.4		no	
t <sub>su</sub>	Setup time, data before LE↓	Data low	0		0.9		ns	
tu.	Hold time, data after LE↓	Data high	Q1		0.9	·	ns	
th	noid time, data arter LE↓	Data low	1.5		1.4		115	

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 30 pF, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

00		, ,				
PARAMETER	FROM	то	SN54ALVTH16373	SN74ALVT	H16373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN MAX	MIN	MAX	UNII
<sup>t</sup> PLH	D	Q	1 3.4	1	3.3	ns
t <sub>PHL</sub>		ď	1 4.3	1	4.2	115
t <sub>PLH</sub>	LE	Q	1.4 3.9	1.5	3.8	ns
t <sub>PHL</sub>	LE	ď	1.4 4.6	1.5	4.5	115
<sup>t</sup> PZH	<del>OE</del>	Q	1.7 4.4	1.8	4.3	
t <sub>PZL</sub>	OE .	ď	1,4 4.1	1.5	4	ns
<sup>t</sup> PHZ	OE	Q	1.4 4.7	1.5	4.6	ns
t <sub>PLZ</sub>			1 3.7	1	3.6	1115

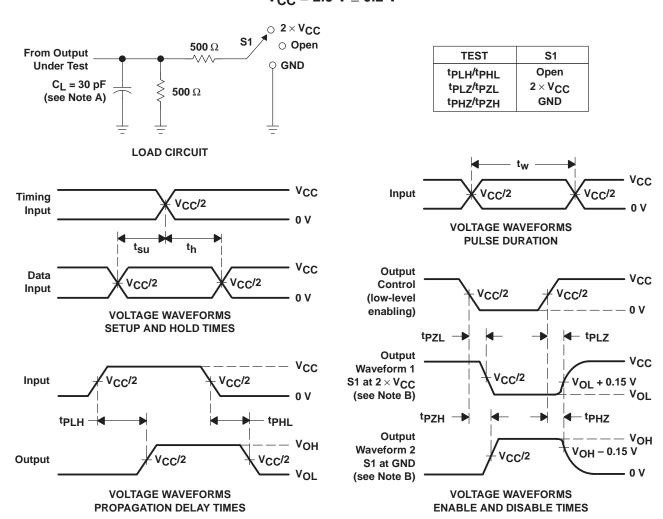
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALVTH16373	SN74ALVTH16373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN MAX	XAM MIM MAX	
tPLH	D	Q	1 3.2	2 1 3.1	]
<sup>t</sup> PHL	D	3	1 3.4	1 3.3	ns
<sup>t</sup> PLH	LE	Q	1 3.4	1 3.3	ns
<sup>t</sup> PHL	LL	ď	1 2 3.6	1 3.5	115
<sup>t</sup> PZH	ŌĒ	Q	1.3 4.1	1.4	ns
<sup>t</sup> PZL	OE	3	3.5	5 1 3.4	. 115
<sup>t</sup> PHZ	ŌĒ	Q	1.4 5	1.5 4.9	ns
t <sub>PLZ</sub>	OE	3	1.4 4.6	1.5 4.5	



SCES067F - JUNE 1996 - REVISED JANUARY 1999

# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



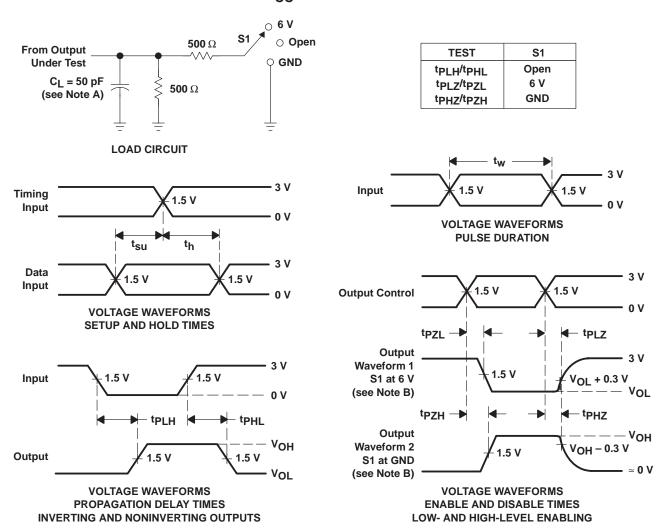
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2$  ns,  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform22 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





26-Aug-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
74ALVTH16373DLG4	ACTIVE	SSOP	DIAWING	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	(3) Level-1-260C-UNLIM	-40 to 85	(4/5) ALVTH16373	Samples
74ALVTH16373DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
74ALVTH16373GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
74ALVTH16373GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
74ALVTH16373VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples
74ALVTH16373VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples
SN74ALVTH16373DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373KR	OBSOLETE	E BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	VT373	
SN74ALVTH16373VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



in homogeneous material)

#### PACKAGE OPTION ADDENDUM

26-Aug-2013

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. **Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

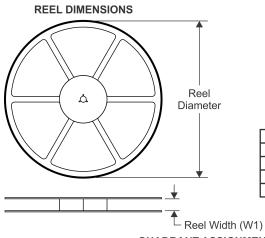
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

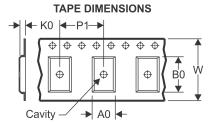
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### **PACKAGE MATERIALS INFORMATION**

www.ti.com 12-Aug-2013

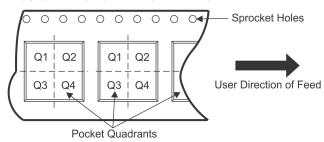
#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

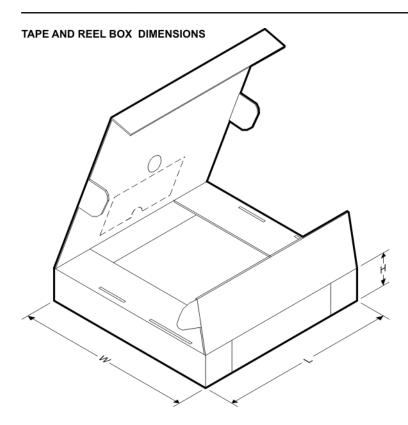
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVTH16373DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH16373GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVTH16373VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

www.ti.com 12-Aug-2013



\*All dimensions are nominal

7 til diritoriorerio di e ricitima:								
Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74ALVTH16373DLR	SSOP	DL	48	1000	367.0	367.0	55.0	
SN74ALVTH16373GR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74ALVTH16373VR	TVSOP	DGV	48	2000	367.0	367.0	38.0	

#### DGV (R-PDSO-G\*\*)

#### 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

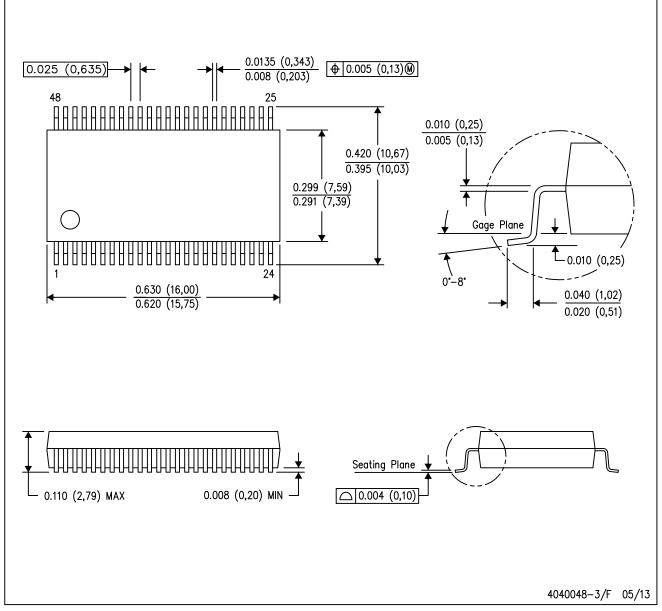
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

## DL (R-PDSO-G48)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

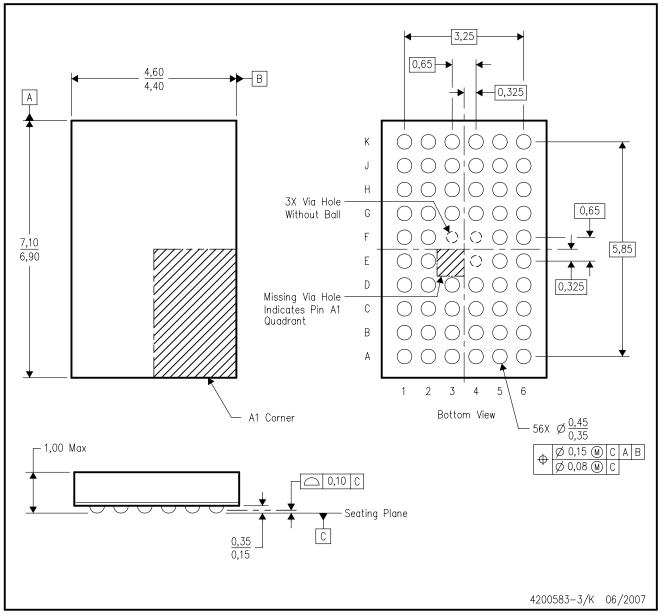
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



## GQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors <a href="www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="e2e.ti.com">e2e.ti.com</a>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>

# AMEYA360 Components Supply Platform

## **Authorized Distribution Brand:**

























#### Website:

Welcome to visit www.ameya360.com

#### Contact Us:

#### > Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

#### > Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

#### Customer Service :

Email service@ameya360.com

## Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com